Semiconductor Device Type:	**D7A**	**SOT-23-3-NiPdAu**			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon	7440-21-3	Die	3.68	0.36	36802
Copper	7440-50-8	Leadframe	36.78	3.62	367786
Iron	7439-89-6	Leadframe	0.96	0.09	9579
Phosphorus	7723-14-0	Leadframe	0.05	0.01	530
Zinc	7440-66-6	Leadframe	0.07	0.01	682
Lead	7439-92-1	Leadframe	0.00	0.00	38
Nickel	7440-02-0	Leadframe	0.19	0.02	1930
Palladium	7440-05-3	Leadframe	0.01	0.00	149
Gold	7440-57-5	Leadframe	0.00	0.00	23
Silver	7440-22-4	Die Attach	2.45	0.24	24521
Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin	9003-36-5	Die Attach	0.31	0.03	3065
1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	Die Attach	0.15	0.02	1533
Dapsone	80-08-0	Die Attach	0.15	0.02	1533
Gold	7440-57-5	Wire	0.22	0.02	2186
Silica Fused	60676-86-0	Molding Compound	48.48	4.77	484786
Epoxy Resin	Trade secret	Molding Compound	2.75	0.27	27482
Phenol Resin	Trade secret	Molding Compound	2.75	0.27	27482
Epoxy, Cresol Novolac	29690-82-2	Molding Compound	0.82	0.08	8245
Carbon Black	1333-86-4	Molding Compound	0.16	0.02	1649
		TOTALS:	**100.00**	**9.84**	**1,000,000**

9.84 mg Total Mass

		Package Homogeneous Materials		
0.36	**(mg) Total**	**Die**	**% of Total Weight**	**3.68**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
3.75	**(mg) Total**	**Leadframe**	**% of Total Weight**	**38.07**
	Copper	7440-50-8	96.60	
	Iron	7439-89-6	2.52	
	Phosphorus	7723-14-0	0.14	
	Zinc	7440-66-6	0.18	
	Lead	7439-92-1	0.01	
	Nickel	7440-02-0	0.51	
	Palladium	7440-05-3	0.04	
	Gold	7440-57-5	0.01	
		Total	**100.00**	
0.30	**(mg) Total**	**Die Attach**	**% of Total Weight**	**3.07**
	Silver	7440-22-4	80.00	
	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin	9003-36-5	10.00	
	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	5.00	
	Dapsone	80-08-0	5.00	
		Total	**100.00**	
0.02	**(mg) Total**	**Wire**	**% of Total Weight**	**0.22**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
5.41	**(mg) Total**	**Molding Compound**	**% of Total Weight**	**54.96**
	Silica Fused	60676-86-0	88.20	
	Epoxy Resin	Trade secret	5.00	
	Phenol Resin	Trade secret	5.00	
	Epoxy, Cresol Novolac	29690-82-2	1.50	
	Carbon Black	1333-86-4	0.30	
9.84		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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